AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claims 1-8 (canceled).

Claim 9 (new): A laminated ceramic electronic component comprising:

a ceramic laminated member;

an inner conductor provided inside of the ceramic laminated member;

an outer electrode provided on the surface of the ceramic laminated member; and

a lead conductor connecting the inner conductor to the outer electrode; wherein

a thickness of the lead conductor is less than a thickness of the inner conductor.

Claim 10 (new): The laminated ceramic electronic component according to claim 9, wherein a conductor width of the lead conductor is greater than a conductor width of the inner conductor.

Claim 11 (new): The laminated ceramic electronic component according to claim 9, wherein the inner conductor defines a coil.

Claim 12 (new): The laminated ceramic electronic component according to claim 9, wherein the inner conductor includes a plurality of inner conductor pattern layers and the lead conductor includes a plurality of lead conductor pattern layers, the number of lead conductor pattern layers of said plurality of lead conductor pattern layers is less

than the number of inner conductor pattern layers of said plurality of inner conductor pattern layers.

Claim 13 (new): The laminated ceramic electronic component according to claim 9, wherein a metal content of the lead conductor is greater than a metal content of the inner conductor.

Claim 14 (new): The laminated ceramic electronic component according to claim 9, wherein the thickness of the inner conductor is in the range of about 70 μm to about 80 μm, and the thickness of the lead conductor is in the range of about 35 μm to about 40 μm.

Claim 15 (new): The laminated ceramic electronic component according to claim 12, wherein the number of inner conductor pattern layers is 10 and the number of lead conductor pattern layers is 5.

Claim 16 (new): The laminated ceramic electronic component according to claim 12, wherein at least one of the inner conductor pattern layers is made of a conductive paste including resin particles that are consumed the firing step.

Claim 17 (new): The laminated ceramic electronic component according to claim 12, wherein each of the plurality of inner conductor pattern layers is substantially U-shaped.

Claim 18 (new): The laminated ceramic electronic component according to claim 12, wherein the inner conductor is a spiral coil.

Claim 19 (new): A method for producing a laminated ceramic electronic component including a ceramic laminated member formed by laminating a plurality of ceramic green sheets, an inner conductor formed inside of the ceramic laminated member, an outer electrode formed on the surface of the ceramic laminated member, and a lead conductor connecting the inner conductor to the outer electrode, the method comprising the steps of:

preparing the ceramic green sheets;

transferring an inner conductor pattern layer and a lead conductor pattern layer formed on a support on the ceramic green sheets in order to form the inner conductor and the lead conductor on the ceramic green sheets;

laminating the ceramic green sheets so as to cover the inner conductor and the lead conductor; and

firing the ceramic laminated member; wherein

in the step of forming the inner conductor and the lead conductor, the inner conductor pattern layer is transferred on the ceramic green sheet a plurality of times so as to overlap each other, thereby forming the inner conductor, and the lead conductor pattern layer is transferred on the ceramic green sheet, wherein the number of times of the transferring is less than the number of times of the transferring of the inner conductor pattern layer, thereby forming the lead conductor having a thickness that is less than a thickness of the inner conductor.

Claim 20 (new): The method for producing a laminated ceramic electronic component according to claim 19, wherein the ceramic laminated member formed by laminating a plurality of ceramic green sheets is a mother ceramic laminated block including a plurality of ceramic laminated members, and the mother ceramic laminated block is cut according to an arrangement of the inner conductor formed inside thereof to provide each ceramic laminated member.

Claim 21 (new): The method for producing a laminated ceramic electronic component according to claim 19, wherein a conductor width of the lead conductor is greater than a conductor width of the inner conductor.

Claim 22 (new): The method for producing a laminated ceramic electronic component according to claim 19, wherein a metal content of conductive paste used for forming the lead conductor pattern layer is greater than that of conductive paste used for forming the inner conductor pattern layer.

Claim 23 (new): The method for producing a laminated ceramic electronic component according to claim 19, wherein at least the inner conductor pattern layer that is in contact with the ceramic green sheet is formed with conductive paste including resin particles that are consumed the firing step.

Claim 24 (new): The method for producing a laminated ceramic electronic component according to claim 19, wherein each of the inner conductor pattern layers is substantially U-shaped.

Claim 25 (new): The method for producing a laminated ceramic electronic component according to claim 19, wherein the thickness of the inner conductor is in the range of about 70 μm to about 80 μm, and the thickness of the lead conductor is in the range of about 35 μm to about 40 μm.

Claim 26 (new): The method for producing a laminated ceramic electronic component according to claim 19, wherein the number of inner conductor pattern layers is 10 and the number of lead conductor pattern layers is 5.

Claim 27 (new): The method for producing a laminated ceramic electronic component according to claim 19, wherein the inner conductor is formed as a spiral coil.